CSE477 VLSI Digital Circuits Fall 2002

Lecture 25: Peripheral Memory Circuits

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[Adapted from Rabaey's Digital Integrated Circuits, ©2002, J. Rabaey et al.]

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Review: Read-Write Memories (RAMs)

Static – SRAM

- data is stored as long as supply is applied
- large cells (6 fets/cell) so fewer bits/chip
- fast so used where speed is important (e.g., caches)
- differential outputs (output BL and !BL)
- use sense amps for performance
- compatible with CMOS technology

Dynamic – DRAM

- periodic refresh required
- small cells (1 to 3 fets/cell) so more bits/chip
- slower so used for main memories
- single ended output (output BL only)
- need sense amps for correct operation
- not typically compatible with CMOS technology

Review: 4x4 SRAM Memory



Peripheral Memory Circuitry

Row and column decoders

Sense amplifiers

Read/write circuitry

Timing and control

Row Decoders

- □ Collection of 2^M complex logic gates organized in a regular, dense fashion
- (N)AND decoder

 $WL(0) = !A_9!A_8!A_7!A_6!A_5!A_4!A_3!A_2!A_1!A_0$

$$WL(511) = !A_9A_8A_7A_6A_5A_4A_3A_2A_1A_0$$

. . .

NOR decoder

 $WL(0) = !(A_9 + A_8 + A_7 + A_6 + A_5 + A_4 + A_3 + A_2 + A_1 + A_0)$

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 $WL(511) = !(A_9 + !A_8 + !A_7 + !A_6 + !A_5 + !A_4 + !A_3 + !A_2 + !A_1 + !A_0)$

Dynamic NOR Row Decoder



Dynamic NAND Row Decoder



Split Row Decoder



Pass Transistor Based Column Decoder



- Advantage: speed since there is only one extra transistor in the signal path
- Disadvantage: large transistor count

Tree Based Column Decoder



Advantage: number of transistors drastically reduced

- Disadvantage: delay increases quadratically with the number of sections (so prohibitive for large decoders)
 - fix with buffers, progressive sizing, combination of tree and pass transistor approaches

Bit Line Precharging



Clocked Precharge



equalization transistor - speeds up equalization of the two bit lines by allowing the capacitance and pull-up device of the nondischarged bit line to assist in precharging the discharged line

Sense Amplifiers



□ Use sense amplifiers (SA) to amplify the small swing on the bit lines to the full rail-to-rail swing needed at the output



Latch Based Sense Amplifier



Alpha Differential Amplifier/Latch



Read/Write Circuitry



D: data (write) bus R: read bus W: write signal CS: column select (column decoder)

Local W (write): BL = D, !BL = !D enabled by W & CS Local R (read): R = BL, !R = !BL enabled by !W & CS

Approaches to Memory Timing



SRAM Address Transition Detection



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DRAM Timing



Review: A Typical Memory Hierarchy

- By taking advantage of the principle of locality:
 - Present the user with as much memory as is available in the cheapest technology.
 - Provide access at the speed offered by the fastest technology.



Caches

Address issued by the data path has to be mapped (in hardware) into a cache address

tag which word in the cache block which cache block in the set

Cache block (aka line) – unit of read/write information in cache

Cache mapping strategies

- Direct mapped
 - A word can be in only one block in the cache, so only have to compare its tag against that block's tag
- Block set associative
 - A word can be in two (or four or eight ...), so have to compare its tag against the tags of those two (or four or eight ...) cache blocks
- Fully associative

- A word can be in any block in the cache, so have to compare its tag against the tags of all of the blocks in the cache

Two-Way Block Set Associative Cache



Translation Lookaside Buffers (TLBs)

- Small caches used to speed up address translation in processors with virtual memory
- All addresses have to be translated before cache access
- □ I\$ can be virtually indexed/virtually tagged

TLB Structure

Address issued by CPU (page size = index bits + byte select bits)







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Reliability and Yield

Semiconductor memories trade-off noise margin for density and performance

Thus, they are highly sensitive to noise (cross talk, supply noise)

High density and large die size causes yield problems

Yield = 100 # of good chips/wafer # of chips/wafer

$$Y = [(1 - e^{-AD})/(AD)]^2$$

Increase yield using error correction and redundancy

Alpha Particles



1 particle ~ 1 million carriers

Yield



Yield curves at different stages of process maturity (from [Veendrick92])

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Redundancy in the Memory Structure



Redundancy and Error Correction



Next Lecture and Reminders

Next lecture

- System level interconnect
 - Reading assignment Rabaey, et al, xx
- Reminders
 - Project final reports due December 5th
 - Final grading negotiations/correction (except for the final exam) must be concluded by December 10th
 - Final exam scheduled
 - Monday, December 16th from 10:10 to noon in 118 and 121 Thomas